

03-30-2006

Form PTO-1595 (Rev. 03-05)
OMB No. 0651-0027 (exp. 6/30/2005)

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To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of conveying party(ies):

Ken-ichi NONAKA (3/16/2006), Hideki HASHIMOTO (3/16/2006), Seiichi YOKOYAMA (3/16/2006), Kensuke IWANAGA (3/16/2006),

Additional name(s) of conveying party(ies) attached? Yes No

2. Name and address of receiving party(ies)

Name: HONDA MOTOR CO., LTD.

Internal Address: _____

Street Address: _____

1-1, Minami-Aoyama 2-chome, Minato-ku
Tokyo
JAPAN

City: _____

State: _____

Country: _____ Zip: _____

Additional name(s) & address(es) attached: Yes No

3. Nature of conveyance/Execution Date(s):

Execution Date(s): in parentheses after inventor name

Assignment Merger Change of Name

Security Agreement Joint Research Agreement

Government Interest Assignment

Executive Order 9424, Confirmatory License

Other _____

4. Application or patent number(s):

This document is being filed together with a new application.

A. Patent Application No.(s)

NEW

B. Patent No.(s)

Additional numbers attached? Yes No

5. Name and address to whom correspondence concerning document should be mailed:

Name: James M. Slattery
BIRCH, STEWART, KOLASCH & BIRCH,
LLP

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6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00

- Authorized to be charged by credit card
- Authorized to be charged to deposit account
- Enclosed
- None required (government interest not affecting title)

8. Payment Information

- a. Credit Card Last 4 Numbers _____
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9. Signature:

James M. Slattery
Signature

March 23, 2006

Date

James M. Slattery - 28,380

Name of Person Signing

Total number of pages including cover sheet, attachments, and documents:

6

113874 U.S. PTO
11/386661
032306

03/24/2006 AKELECHI 00000008 11386661

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Birch, Stewart, Kolasch & Birch, LLP

JMS/dns

PATENT
REEL: 017724 FRAME: 0459

Additional Conveying Party(ies)/Execution Date(s) (1. Continued):

Yoshimitsu SAITO (3/16/2006), Hiroaki IWAKURO (3/16/2006), Masaaki SHIMIZU (3/16/2006), Yusuke FUKUDA (3/16/2006), Koichi NISHIKAWA (3/16/2006), and Yusuke MAEYAMA (3/16/2006)

Additional Assignees (2. Continued):

Assignee Name: Shindengen Electric Manufacturing Co., Ltd.

Internal Address:

Street Address: 2-1. Ohtemachi 2-chome, Chiyoda-ku
Tokyo
JAPAN

City: _____ State: _____ Country: _____ Zip: _____

Assignee Name: _____

Internal Address:

Street Address:

City: _____ State: _____ Country: _____ Zip: _____

Assignee Name: _____

Internal Address:

Street Address:

City: _____ State: _____ Country: _____ Zip: _____

Additional Applications and/or Patents (4. Continued):

Additional Patent Application Numbers
4A. Continued:

Additional Patent Numbers
4B. Continued:

Additional numbers attached?

Yes No

BIRCH, STEWART, KOLASCH & BIRCH, LLPUNITED STATES PATENT RIGHTS, OR
UNITED STATES PLUS ALL FOREIGN PATENT RIGHTS**ASSIGNMENT**Application No. NEWFiled March 23, 2006**Insert Name(s)
of Inventor(s)*******(Given Name FAMILY NAME (ALL CAPS))*****

WHEREAS,	<u>Ken-ichi NONAKA</u>	:	<u>Hideki HASHIMOTO</u>
	<u>Seiichi YOKOYAMA</u>		<u>Kensuke IWANAGA</u>
	<u>Hiroaki IWAKURO</u>		<u>Masaaki SHIMIZU</u>
	<u>Koichi NISHIKAWA</u>		<u>Yusuke MAEYAMA</u>

(hereinafter designated as the undersigned) has (have) invented certain new and useful improvements in

**Insert Title
of Invention**METHOD FOR MANUFACTURING JUNCTION SEMICONDUCTOR DEVICE

for which an application for Letters Patent of the United States of America has been executed by the undersigned (except in the case of a provisional application).

**Insert Date
of Signing of
Application**on March 16, 2006; and**Insert Name
of Assignee**WHEREAS, (A): Honda Motor Co., Ltd.
(B): Shindengen Electric Manufacturing Co., Ltd.**Insert Address
of Assignee**(A): 1-1, Minami-Aoyama 2-chome, Minato-ku, Tokyo, Japan
(B): 2-1, Ohtemachi 2-chome, Chiyoda-ku, Tokyo, Japanits heirs, successors, legal representatives and assigns (hereinafter designated as the Assignee) is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent(s) that may be granted therefor in the United States of America and in any foreign countries.**CHECK BOX
IF APPROPRIATE**

NOW, THEREFORE, in consideration of the sum of Ten Dollars (\$10.00) to the undersigned in hand paid, the receipt of which is hereby acknowledged, and other good and valuable consideration, the undersigned has (have) sold, assigned and transferred, and by these presents does sell, assign and transfer unto said Assignee the full and exclusive right to the said invention in the United States of America, its territories, dependencies and possessions and the entire right, title and interest in and to any and all Letters Patent(s) which may be granted therefor in the United States of America, its territories, dependencies and possessions, and if the box above is designated, in any and all foreign countries;

and to any and all divisions, reissues, continuations, conversions and extensions thereof for the full term or terms for which the same may be granted.

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional, conversion or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree (s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division, conversion or reissue thereof or Letter Patent(s) or reissue patent issued thereon and to cooperate with the Assignee in every way possible in obtaining and producing evidence and proceeding with such interference.

The undersigned agree(s) to execute all papers and documents and to perform any act which may be necessary in connection with claims or provisions of the International Convention for the Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States of America patent(s) or a grant of a valid United States of America and any foreign patent(s) to the Assignee and to vest all rights therein hereby conveyed to said Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

The undersigned hereby authorize(s) and request(s) the Patent and Trademark Office Officials in the United States of America and in any foreign countries to issue any and all Letters Patents resulting from said application or any continuing, divisional conversion or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) the full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) the law firm of Birch, Stewart, Kolasch & Birch, LLP the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the rules of the U.S. Patent and Trademark Office for recordation of this document.

The undersigned hereby covenant(s) that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

Date <u>March 16, 2006</u>	Name of Inventor <u>Ken-ichi NONAKA</u> (signature) <i>Kenichi Nonaka</i>
Date <u>March 16, 2006</u>	Name of Inventor <u>Hideki HASHIMOTO</u> (signature) <i>Hideki Hashimoto</i>
Date <u>March 16, 2006</u>	Name of Inventor <u>Seiichi YOKOYAMA</u> (signature) <i>Seiichi Yokoyama</i>
Date <u>March 16, 2006</u>	Name of Inventor <u>Kensuke IWANAGA</u> (signature) <i>Kensuke Iwanaga</i>
Date <u>March 16, 2006</u>	Name of Inventor <u>Yoshimitsu SAITO</u> (signature) <i>Yoshimitsu Saito</i>
Date _____	Name of Inventor <u>Hiroaki IWAKURO</u> (signature)

June 2002

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional, conversion or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree (s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division, conversion or reissue thereof or Letter Patent(s) or reissue patent issued thereon and to cooperate with the Assignee in every way possible in obtaining and producing evidence and proceeding with such interference.

The undersigned agree(s) to execute all papers and documents and to perform any act which may be necessary in connection with claims or provisions of the International Convention for the Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States of America patent(s) or a grant of a valid United States of America and any foreign patent(s) to the Assignee and to vest all rights therein hereby conveyed to said Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

The undersigned hereby authorize(s) and request(s) the Patent and Trademark Office Officials in the United States of America and in any foreign countries to issue any and all Letters Patents resulting from said application or any continuing, divisional conversion or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) the full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

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In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

Date _____,	Name of Inventor <u>Ken-ichi NONAKA</u> (signature)
Date _____,	Name of Inventor <u>Hideki HASHIMOTO</u> (signature)
Date _____,	Name of Inventor <u>Seichi YOKOYAMA</u> (signature)
Date _____,	Name of Inventor <u>Kensuke IWANAGA</u> (signature)
Date _____,	Name of Inventor <u>Yoshimitsu SAITO</u> (signature)
Date <u>March 16, 2006</u> ,	Name of Inventor <u>Hiroaki IWAKURO</u> (signature)

Hiroaki Iwakuro

June 2002

Date March 16, 2006,

Name of Inventor Masaaki SHIMIZU
(signature) *Masaaki Shimizu*

Date March 16, 2006,

Name of Inventor Yusuke FUKUDA
(signature) *Yusuke Fukuda*

Date March 16, 2006,

Name of Inventor Koichi NISHIKAWA
(signature) *Koichi Nishikawa*

Date March 16, 2006,

Name of Inventor Yusuke MAEYAMA
(signature) *Yusuke Maeyama*

Date March 16, 2006,

Name of Inventor _____
(signature)

Date _____,

Name of Inventor _____
(signature)

Date _____,

Name of Inventor _____
(signature)

Date _____,

Name of Inventor _____
(signature)

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(signature)

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Name of Inventor _____
(signature)

Date _____,

Name of Inventor _____
(signature)

Date _____,

Name of Inventor _____
(signature)

June 2002